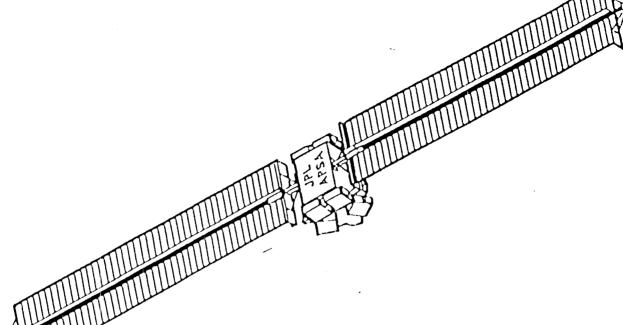




Reverse Bias Characteristics of Thin BSF/BSR Silicon Sola™ C⊕ s For Advanced Photovoltaic Solar Array (APSA)

Hans Schurig TRW Space & Electronics Group Redond Beach, CA Paul Stella Jet Propulsion Laboratory California hstitute of Technology Pasadena, CA Presented at the 1993 Space Power Workshob 20-22 April 1993 Albuquerque, New Mexico Work sponsored by the Jet Propulsion Laboratory, California Institute of Technology, under contract with the National Aeronautics and Space Administration



REVERSE BIAS TESTING OF THINBSF/BSR CELLS BACKGROUND

- •A RECENT STUDY CONCLUDED THAT APSA SOLAR ARRAY CIRCUIT PROTECTION IS REQUIRED TO COUNTERACT THE EFFECTS OF HOTSPOTS GENERATED BY
 - SHADOWED CELLS AND
 - CRACKED CELLS.
- REVERSE CHARACTERISTICS OF THINBSF/BSR SILICON CELLS ARE NOT WELL ENOUGH UNDERSTOOD TO DETERMINE THE NEED FOR BYPASS DIODES, PERFORM TRADE-OFF STUDIES, AND TAILOR THE APSA SOLAR ARRAY DESIGN.
- CIRCUIT PROTECTION WOULD HAVE A MAJOR IMPACT ON BLANKET DESIGN AND MANUFACTURING COMPLEXITY.
- NEED FOR EXPERIMENTAL DATA BASE OF THE CELL REVERSE BIAS CHARACTER! ISTICS AND DETERMINE THEIR EFFECTS ON PV PROPERTIES OF THE DEVICES.

APSA SOLAR CELL REVERSE BIAS TEST PROGRAM TEST MATRIX

- •INVESTIGATED THE FOLLOWING ENVIRONMENTAL EFFECTS AND IMPACTS OF OPERATIONAL STRESSES INDUCED ON APSA CELLS UNDER REVERSE BIAS CONDITIONS:
 - A. CURRENT DENSITY EFFECTS TO DETERMINE THE THRESHOLD OF FAILURE DURING REVERSE BIASING.
 - B. PULSED REVERSE BIAS TESTING.
 - C. LONG DURATION REVERSE BIASTESTING.
 - D. CELL REVERSE CHARACTERISTICS AS A FUNCTION OF TEMPERATURE.
 - E. EFFECTS OF CHARGED PARTICLE IRRADIATION ON CELL REVERSE BIASING.
- PERFORMED FAILURE MODES ANALYSIS AFTER CONCLUSION OF TESTS.

CURRENT DENSITY EFFECTS ON CELL REVERSE BIASING TEST ARTICLES/TEST DESCRIPTION

• TEST ARTICLES:

-32 PRODUCTION GRADE, THIN BORON-DIFFUSED BSF/BSR SILICON SOLAR CELLS, FABRICATED BY VENDOR A, 2.5 X 5.1 X 0.007 CM, COVERED WITH 0.005 CM THICK UVR COATED CERIUM-DOPED BOROSILICATE GLASS.

• TEST SEQUENCE:

- INITIAL P-V CHAR ACT ERISTICS (AMO, @ 28 C).
- REVERSE BIAS TESTS (RBT) AT AMBIENT CONDITIONS.
 - * REVERSE CURRENT WAS INCREASED IN INCREMENTAL STEPS OF 100 mA TO CELL BREAKDOWN VOLTAGE.
 - * RBT WERE MADE AFTER READINGS HAD STABILIZED.
 - * PV MEASUREMENTS TAKEN AFTER EACH RBT.
- SOME CELLS WERE TAKEN TO FAILURE TO ESTABLISH THE THRESHOLD OF FAILURE.

CURRENT DENSITY EFFECTS ON REVERSE CHARACTERISTICS. RESULTS FOR CELLS FABRICATED BY VENDOR A

- . RESULTS INDICATE WIDELY DISTRIBUTED REVERSE CHARACTERISTICS OF CELLS FABRICATED BY VENDOR A:
 - 15% EXHIBITED LOW VOLTAGE (VI < 20 V), YIRH CURRENT (> 0.5 Isc). CELL Isc APPROX. 520 mA.
 - 13% FELL WITHIN INTERMEDIATE VOLTAGE (Vr BETWEEN 20 V AND 40 V) AN I CURRENT RANGE (APPROX. 0.5 Isc).
 72% HAD HIGH VOLTAGE (Vr > 40 V), AND A LOW REVERSE CURRENT (< 0.5 Isc).
- 12 OF THE 32 CELLS (38°/0) WERE TAKEN TO FAILURE:
 - -6 CELLS SHUNTED.
 - -6 CELLS SHORTED.
- NONE OF THE SAMPLES FAILED 'OPEN CIRCUIT".
- POWERDISSIPATION AT FAILURE RANGED FROM ().2 TO 2.3 W/CM² AND AVERAGE DISSIPATION OF UN FAILED CELLS WAS 0.85 W/CM².
- . PV CHARACTER |ST|CS OF UN FAILED CELLS WERE NOT AFFECTED BY RBT.

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FIGURE 2-4. GROUP 9: REVERSE BIAS TESTING UNFAILED CELLS 300 REVERSIE CUIRRE : 44 250 -70 -85 -80 -55 -50 -45 -40 -35 -30 -25 -20 -15 --10 -5

DEMEDSE NO, LOSE (A)

CURRENT DANS TY AFFACTS ON REVARSE CHURACTER STICS RESULTS FOR CELLS FABRICATED BY VENDOR B

- STEADY STATE REVERSE BIAS TESTS WERE A LSO PERFORMED ON THIN BSF/BSR CELLS FABR CATED BY VENDOR B W TH ON- MPLANTATION
- REVERSE CHARACTERISTICS OF VENDOR B CELLS FALL NTO PREDICTABLE CURRENT VOLTAGE RANGE.
- -100% EXH = TED H GH VOLTAGE (Vr 46 V) AND LOW CURRENT (APPROX °.2 isc) BASED ON A QU®NTITY OF 12 DEVICES.
- FIVS OF THE TWELVE CELLS WERE TAKEN TO FA LURE:
- 1 CELL SHUNTED
 4 CELLS SHORTED.
- NONE OF TH≷ SAMPLES FAILED "OPEN CIRCUIT".
- PV CH®RACT≤RIST CS OF UNFAILED CE. ² WERE NOT AFFECT≼D BY

FIGURE 2-8. IR8D THIN CELLS: REVERSE BIAS TESTING FRILED CELLS 200 -180 150 (MM) REVERSEE CURREENT -78 -65 -68 -58 -58 -45 -48 -35 -38 -25 -28 -15 -18 -5

FIGURE 2-7. IR&D THIN CELLS: REVERSE BIRS TESTING UNERTHED CELLS 200 180 150 $(\Pi\Pi)$ 120 Z~ $\bigcup_{i \in I} (x_i)$ 313V 313S 3 80 -y-z 20 -65 -60 -55 -50 -45 -40 -35 -30 -25 -20 -15 -19

REPETITIVELY PULSED REVERSE BIAS TESTING TEST ARTICLES/TEST DESCRIPTION

• PURPOSE:

- TO INVESTIGATE THE EFFECTS OF RAPID SHADOWING CYCLES ON UNDAMAGED AND FRACTURED SOLAR CELLS.

TEST ARTICLES:

12 PRODUCTION GRADE, THIN BORON-DIFFUSED BSF/BSR SILICON SOLAR CELLS, FABRICATED BY VENDOR A. CELLS BONDED individually ONTO A 6 X 6 INCH HARD ANODIZED ALUMINUM PLATE.

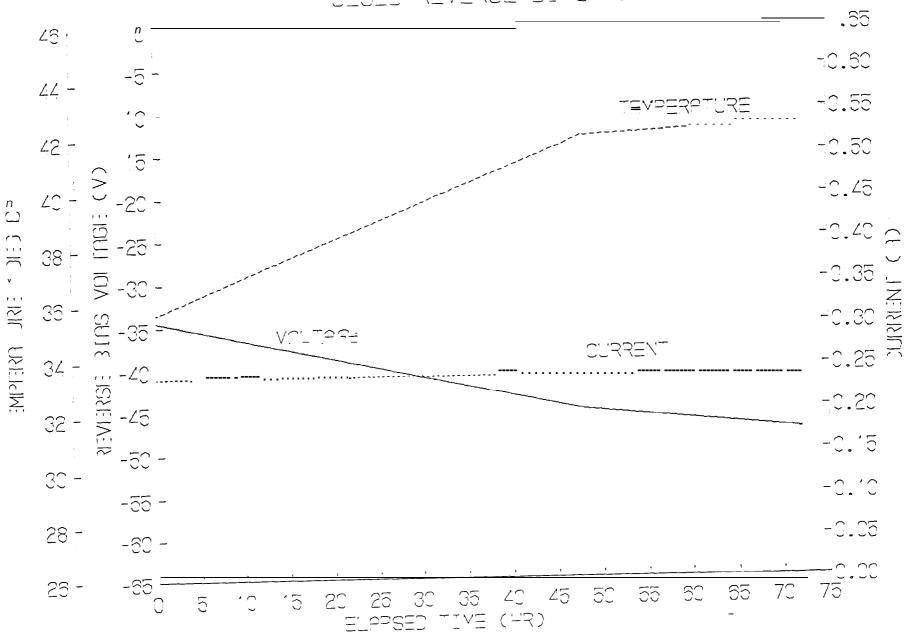
•TEST SEQUENCE:

- INITIALLY PV CHARACTERISTICS AND STEADY STATE REVERSE BIAS MEASUREMENTS WERE TAKEN TO ESTABLISH EACH CELL'S PERFORMANCE AND THRESHOLD OF FAILURE DUE TO RBT.
- CELLS WERE THEN SUBJECTED TO 525,000 RAPID REVERSE BIAS PULSES CLOSE TO BUT NOT EXCEEDING THEIR INDIVIDUAL Vbr RATING. TYPICAL PULSE CYCLE WAS 0.25 SECONDS ON, 0.25 SECONDS OFF. REVERSE CHARACTERISTICS WERE MONITORED DURING THE TEST.
- THEREAFTER PV CHARACTERISTICS AND STEADY STATE REVERSE BIAS MEASUREMENTS WERE REPEATED.

REPETITIVELY PULSED REVERSE BIAS TESTING. RESULTS

- •ALL TWELVE CELLS SURVIVED THE PULSED REVERSE BIAS TEST.
- •NINE OF THE TWELVE CELLS MONITORED DURING THE TEST RETAINED 'A FAIRLY CONSTANT ELECTRICAL PROFILE.
- THE RESULTS OF THE REMAINING 3 CELLS VARY QUITE SIGNIFICANTLY:
 - THE REVERSE VOLTAGE (Vr) FOR TWO OF THE CELLS INCREASED BY APPROX.34% AT CONSTANT CURRENT.
 - THE Vr OF THE THIRD CELL DECREASED BY 25% AT NEARLY CONSTANT CURRENT. THIS DEVICE EVENTUALLY SHUNTED DURING THE STEADY STATE RBT.
- THE PV CHARACTERISTICS OF THE ELEVEN UN FAILED CELLS WERE NOT AFFECTED BY THIS TEST.

FIGURE 3-11. APSA THIN ST SOLAR CELL S/N 14 PULSED REVERSE BIAS TEST



Egure 3-16. Summary of Repetitively Pulsed Revierse Bias Test Results

 ייייייייייייייייייייייייייייייייייייייי	eristics	1,701	(%)	oma out		0.00			01 0.87	-0.07 0.00	<u> </u>	-0.6//2.0-	-0.07	1	0.26 0.04	0.73	-	0.00	0.08 0.22	21.0-	1	0.19 0.24		
בווסיסיסיום.	Characteristics		Change (%)		V OC	0.10	<u> </u>	-0.08 0.21	0.01	<u> </u> 	$\frac{1}{1}$	-1.50 [-0.	<u> </u>	0.00	-0.08 0-			00:0	-0.16		-0.08	0 8 0	1	
Reverse	00:+0::	Characteristics	(%) 6000040	10/10/0	le Current	C K		os.	 	_ _ 	7.3	42	-	5)	2 %	-	2.0	-14.			-3.1		0.0-	
		Cha			Final Voltage	1	43.8		1	187.0	122.4 5.4	077.0	75 2 67	3.7	1	7.007	234.6 38.4	23		245.0 7.3	0.08 20.0	+	185.5	
				Reverse Current (mA)	0:4:0		0 077	1	237.0	210.6	1107	<u> </u>	241.2	<u> </u> 		257.2	777	000	1.5.0	249.6		7.007	7807	
				Voltage (V)		Fino			33.0	57.8	100	6.04	7.77	100	22.8	8.8		-1	57.9	212	- -	54.1	(T	-
				Boverse Voltage	00.000			53.0	31.0	54.2	,	44.1	23.0	5.50	16.2	0 2	1	1.10	55.6		5./7	6.7	1	, 1, 1, 1
				100	ا ۋ			4	rc.	o C		/	c	Ω	4	3.5	3	7	7,6	ין י	/ }	¢χ.	-	9

LONG DURATION REVERSE BIAS TESTING TEST ARTICLES/TEST DESCRIPTION

opurposE:

- TO INVESTIGATE THE EFFECTS OF EXTENDED PERIODS OF SHADOWING OR CRITICAL CELL BREAKAGE.

. TEST ARTICLES:

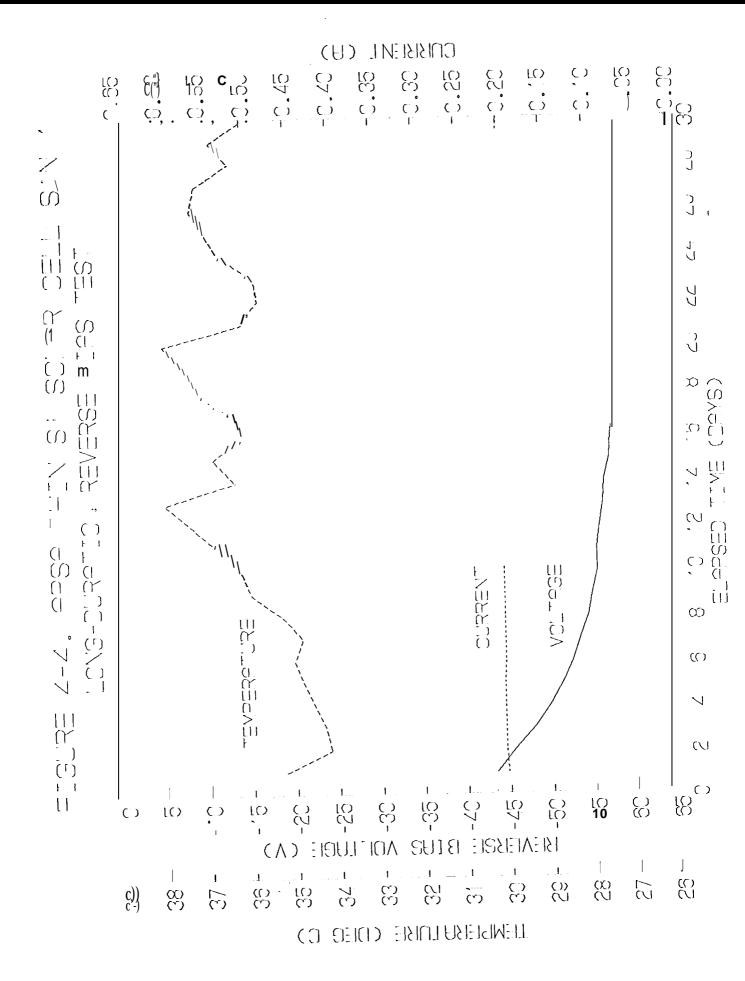
-8 PRODUCTION GRADE, THIN BORON-D! FFUSEDBSF/BSR SILICON CELLS FABRICATED BY VENDOR A. CELLS BONDED INDIVIDUALLY ONTO A 6 X 6 IN CHHARD ANODIZED ALUMINUM PLATE (HEAT SINK).

• TEST SEQUENCE:

- INITIALLY PV CHARACTERISTICS AND STEADY STATE REVERSE BIAS MEASUREMENTS WERE TAKEN TO ESTABLISH EACH CELL'S PERFORMANCE AND THRESHOLD OF FAILURE DUE TO RBT.
- CELLS WERE THEN EXPOSED TO CONTINUOUS 30-DAY REVERSE BI ASING CLOS E TO BUT NOT E XCEEDING THEIR INDIVIDUAL Vbr RATING. REVERSE CHARACTERISTICS WERE MONITORED DURING THE TEST.
- THEREAFTER PV CHARACTERISTICS AND STEADY STATE REVERSE BIAS MEASUREMENTS WERE REPEATED.

LONG DURATION REVERSE BIAS TESTING RESULTS

- ALL EIGHT CELLS SURVIVED THE LONG DURATION RBT EXPOSURE.
- •THEIR REVERSE CHARACTERISTICS WERE AFFECTED TO DIFFERENT DEGREES.
- •INGENERAL, THE CELLS REVERSE BIAS VOLTAGE TENDED TO INCREASE GRADUALLY INTIMEWHILETHE REVERSE CURRENT WAS SEEN TO DECREASE SLOWLY.
 - ON AVERAGE, VriNCREASEDBY ?1.2°/0, ir DECREASED BY 14.2%.
 - Vr RANGED FROM -2.3% TO 35.670, Ir DECREASED **BETWEEN -0.370.** AND -52.6% FOR **THE EIGHT CELLS.**
- THE PV MEASUREMENTS INDICATE THAT THE AVERAGE Isc DECREASED BY 14.3%, WHILE Pmax WAS REDUCED BY 14.8%.



eigure 4-12. Summary of Long Duration Reverse ∋iasing Test ≍esui∿s

	SS			Pmp	-14.8		-15.0	-14.5		-14.5	-15.3	L	- 5.0	-14.8	1/15	2.1	
Photovoltaic	Characteristics	(%) 000040	Cilaliga	Isc			-14.2	14.2	7	-14.0	-14.8	>-	-14.4	-14.4	0 %	7.4.	
				Voc			-0.4		 :5	-0.5	0	2	8.0	-0.7	, ,	7.0-	
Reverse			Chande (%)	Current	2	7.:-	000	5	∞. •	-102	1.2		-21.1	2001	-52.5	-17.3	
Say			Chan	0004,0/1	י אטייאמע		5.00	/: -	75.7	7 17	2.6	-2.3	0,7	2	8.5	0 8	3:5
			1 V w/ + uozz	יייין אייין	roo:	7 000	4.007	295.3	2007	230.2	162.4	2008	2007	0.40	82.4	0,00	2
			١	Keverse Current Number	1 1		202.8	297.3	7 000	300.5	201.0	, 600	000	196.3	173.8	1	184.7
		-		o'tage (V)			50.0	00		35.8	50.7		α.5	60.5	7 00		20.7
				Reverse Voltage	lui+in!		43.5	120	7.7	31.8	527	75.7	ω ω.	54.3	L	55.8	0 8 11
		-	İ	Cell	2	2	-	c	3 3	10	10	7	ည	20	2	7.	0

TEMPERATURE EFFECTS ON CELL REVERSE PROPERTIES TEST ARTICLES/TEST DESCRIPTION

• PURPOSE:

- TO DETERMINE THE CELLS'S REVERSE BIAS THRESHOLD AS A FUNCTION OF TEMPERATURE.

. TEST ARTICLES:

-32 PRODUCTION GRADE, BORON-DIFFUSED BSF/BSF THIN SILICON CELLS FABR!CATED BY VENDOR A.

DEVICES WERE BONDED ONTO 5.6" X 7.7' HARD ANODIZED ALU MINUM PLATES (HEAT SINK), 8 CELLS PER PLATE.

- TEST ARTICLES WERE INSTALLE D INTO VACUUM CHAMBER (70 TORR).

TEST SEQUENCE:

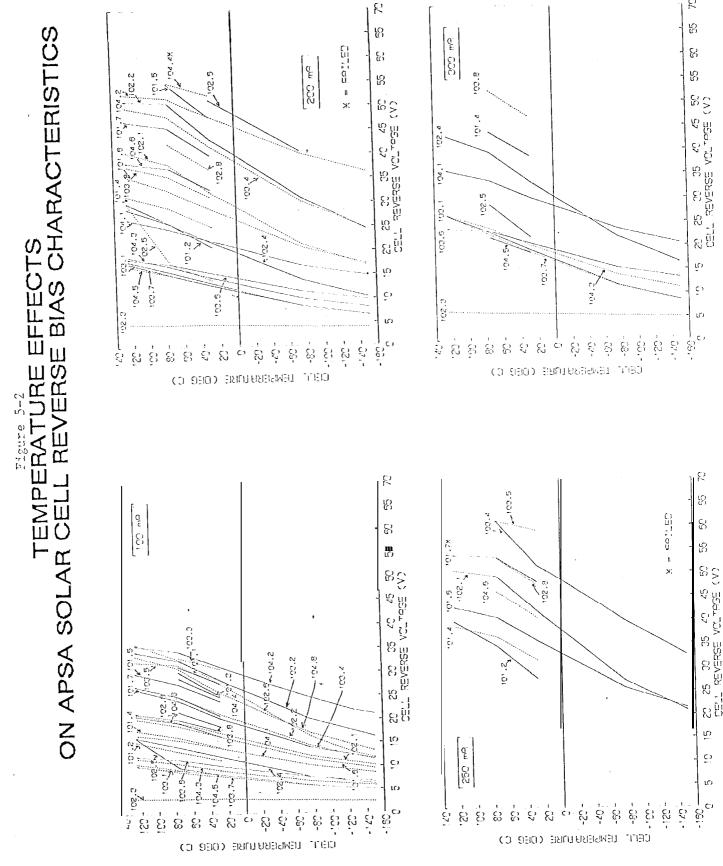
- INITIALLY PV CHARACTERISTICS AND STEADY **STATE RBT WERE TAKEN AT 28 C TO ESTABLISH EACH CELL'S BASELINE RESPONSE AND THE TRESHOLD OF FAILURE DUE TO RBT.**
- DURING RBT THE CELLS WERE STRESSED AT INCREASINGLY HIGHER VOLTAGES AND CURRENTS.
- THEREAFTER, THE PV AND RBT MEASUREMENTS WERE REPEATED SEQUENTIALLY AT 75 C, 125 C, -75 C, AND -150 C.

T'EMPERATIONE EFFECTS ON CELL' REVERSE PROPERTIES RESULTS

- THE CELLS' Vr INCREASED WITH INCREASING ENVIRONMENTAL
 TEMPERATURES AND CORRESPONDINGLY DECREASED WITH DECREASING
 TEMPERATURES.
- CELL FAILURES OCCURED ONLY DURING TESTING AT ELEVATED TEMPER ATURES. THE TOLLOWING CELL FAILURES WERE RECORDED DURING RBT:

		F FAI LURES
TEMPERATURE (C)	SHORTED	SHUNTED
-150	0	0
- 7 5	0	0
28	0	2
75	3	1
125	1	7

- PV CHARACTERISTICS OF THE 17 UNDAMAGED CELLS REMAINED UNAFFECTED.
- Pmax OF THE 10 SHUNTED CELLS DECREASED BY AN AVERAGE OF 60.6%; THE Voc OF THE SHORTED DEVICES DROPPED BY 68%.



EFFECTS OF CHARGED PARTICLE IRRADIATION TEST ARTICLES/TEST DESCRIPTION

• PURPOSE:

- TOINVESTIGATE THE EFFECTS OF ELECTRON AND PROTON IRRADIATION (APSA MISSION ENVIRONMENT) ON CELL PV AND REVERSE BIAS CHARACTERISTICS.

• TEST ARTICLES:

-10 PRODUCTION GRADE, UNGLASSED BORON-DIFFUSED BSF/BSR THIN SILICON CELLS FABRICATED BY VENDOR A.

•TEST DESCRIPTION:

INITIALLY PV CHARACTERISTICS AND STEADY STATE RBT WERE TAKEN AT 28 C TO ESTABLISH EACH CELL'S ELECTRICAL CHARACTERISTICS.

CHARGED PARTICLE IRRADIATION:

- * 5 CELLS IRRADIATED WITH 1 MeV ELECTRONS TO 1E15 E/CM
- * 5 CELLS IRRADIATED WITH 6 MeV PROTONS TO 1E11P/CM² THEREAFTER PV CHARACTERISTICS AND STEADY STATE RBT WERE REPEATED.

EFFECTS OF CHARGED PARTICLE IRRADIATION RESULTS

- ALL CELLS SURVIVED THIS TEST PHASE; ONE CELL FAI LED DUE TO UNINTENTIONAL OVERSTRESS.
- THE REVERSE CHARACTERISTICS OF THE CELLS WERE NOT GREATLY AFFECTED BY EXPOSURE TO THE CHARGED PARTICLE ENVIRONMENT.
 - Vr AT **CONSTANT CURRENT INCREASED BY** AN AVERAGE OF 6.7% FOR PROTON IRR ADIATED CELLS.
 - 5.3% FOR ELECTRON IRRADIATED CELLS.
- CHARGED PA RTICLE IRRADIATION SEVERELY AFFECTED CELL OUTPUT:
 - Pmax DEGRADED BY
 - 37% FOR CELLS RRADIATED WITH PROTONS
 - 32% FOR CELLS RRADIATED WITH ELECTRONS.

Figure 6-3. Radiat on Effects on APSA Solar Cell Characteristics Summary of Proton Irradiation Data (4 Cells**)

Radiation Effects on PV Characteristics									
	ı Pre-	ı Post-	%						
Parameter	Irradiation	Irradiation	N'et						
Avg. Voc (V)	0.s1194	0.53711	87.77%						
Avg.isc (A)	0.52953	0.41739	78.82%						
Avg. Vmp (V)	0.50940	0.44225	86.82%						
Avg. imp (A)	0.49922	0.39196	78.51%						
Avg. Pmax (W)	0.25424	0.17327	68.15%						
Avg. Fill Factor	0.78459	0.77290	98.51%						

Rad. and Rev. Biasing Effects on PV Characteristics									
Doromotor	Pre- Irradiation	Post-	% Net						
Parameter	madiation	irradiation	IVEL						
Avg. Voc (V)	0.58584	0.53760	91.77%						
Avg. Isc (A)	0.52786	0.41764	79.12%						
Avg. Vmp (V)	0.50903	0.44165	85.76%						
Avg. Imp (A)	0.49620	0.39269	79.14%						
Avg. Pmax (W)	0.25240	0.17336	68.68%						
Avg. Fill Factor	, 0.78278	0.7777255	98.64%						

pre-/Dos:-Irradia-ion Reverse Bias Characteristics									
Cel!	(r	Vr	%						
ID No.	(mA)	Pre-Irrad.	Post-Irrad.	Net					
255	175	35.6	39.8	108.74%					
307	100	57.9	55.3	95.51%					
315	225	35.6	36.2	101.69%					
318**	150	51.3	57	111.11%					
324	200	45.2	53.9	1?5.57%					

^{**} Cell ID No. 318 failed.

Figure 6-2. Radiation Effects on APSA Solar Cell Characteristics
Summary of Electron irradiation Data (5 Cells)

RadiationEffects on PV Characteristics									
Parameter	Pre- Irradiation	Pos:- !rradiation	% Net						
Avg. Voc (V)	0.s?28\$?	0.50928	83.09%						
Avg. Isc(A)	0.52993	0.40283	76.02%						
Avg. Vmp (V)	0.51045	0.42344	82.95%						
Avg.imp (A)	0.49588	0.37746	76.12%						
Avg. Pmax (W)	0.25323	0.15975	63.08%						
Avg. Fill Factor	0.77970	0.77788	99.77%						

Rad.and Rev. Biasing Effects on PV Characteristics									
Parameter	Pre- Irradiation	Post- Irradiation	% Net						
Avg. Voc(V)	0.61143	0.50957	83.35%						
Avg. Isc (A)	0.52799	0.40297	76.32%						
Avg. Vmp (V)	0.51074	0.42441	83.10%						
Avg. Imp (A)	0.49135	0.37639	76.60%						
Avg. Pmax (W)	0.25069	0.15976	63.73%						
Avg. Fill Factor	0.77859	0.77787	99.91%						

Pre-/Post-Irradiation Reverse Bias Characteristics									
Cell	lr.	Vr	%						
ID No.	(mA)	Pre-Irrad.	Post-Irrad.	Net					
270	225	8.1	8.2	101.23%					
277	75	55.1	52.8	96.47%					
285	300	36.8	39.1	106.25%					
291	1 54/175	56.1	66	117.65%					
302	′200	31.2	32.8	105.13%					

APSA CELL FAILURE MODES ANALYSIS

- CELLFAILUPES ARELTHE RESULT OF STRESSES INDUCED DURING REVERSE BIASING SUCH THAT CATASTROPHIC JUNCTION BREAKDOWN RESULTS.
- A VARIETY OF DEFECTS ARE CREATED IN THE CELL STRUCTURE AS A CONSEQUENCE OF FAILURE:
 - THERMALLY INDUCED DECOMPOSITION OF MATERIALS.
 - EVAPORATION OF MATE RIALS.
 - ABSORPTION OF METALS INTO THE SILI CON CRYSTAL LATTICE.
 - -SOLDER REFLOW.
 - STRIATIONS EMANATING FROM THE BREAKDOWN SITE ON CELL BACK SIDE.
- •PHYSICAL DAMAGE AND PROCESSES WERE OBSERVED/ANALYZED WITH:
 THERMOGRAPHY TO OBSERVE THE FORMATION OF HOT SPOTS.
 [R CAMERA WHICH ALLOWS IDENTIFICATION OF DEFECT SITES.
 SCANNING ELECTRON MICROSCOPE (SEM).
 ENERGY DISPERSIVE X-RAYS (EDX) USED TO IDENTIFY LAYERING
 SYSTEM.
 - ELECTRON BEAM INDUCED CURRENTS (EBIC) TO LOCATE DAMAGE SITE WITHIN THE DEVICE STRUCTURE.

APSA CELL FAILURE MODES ANALYSIS CONCLUSIONS

- REVERSE BIAS FAILURES OF CELLS ARE INSTANTANEOUS AND CATASTROPHIC.
- . CELL FAILURES ARE DUE TO JUNCTION SHORTING OR SHUNTING.
- o OPEN CIRCUIT FAILURES 'HAVE NOT BEEN OBSERVED.
- . AT FAILURE THE CELL TEMPERATURE IN THE 'BREAKDOWN REGION EXCEEDS 1400 C. MELTING AND POSSIBLY EVAPORATION OF CELL MATERIALS ARE THE CONSEQUENCE.
- SOLDER SCAVENGING OF THE CONTACT ME TALL IZATION, AND POSSIBLE DECOMPOSITION OF MATERIALS WITH SUBSEQUENT CELL SHUNTING WAS NOT OBSERVED.
- . LOCAL SOLDER REFLOW WAS OBSERVED BUT AFFECTED AREA WAS TOO SMALL TO IMPACT THE INTERCONNECTOR SYSTEM.
- CELL STRESS FRACTURES COULD NOT BE ASSOCIATED WITH REVERSE BIASING. THEY ARE DIFFICULT TO DETECT AND MOST LIKELY THE RESULT OF MECHANICAL STRESSES INDUCED BY HANDLING.

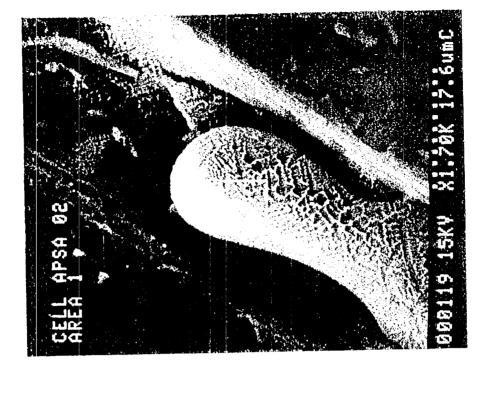
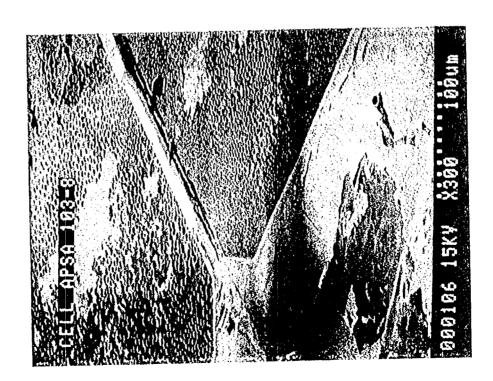


Figure 6A. 400 x Magnification

sigure 5**⅓** 1700 × Magnification



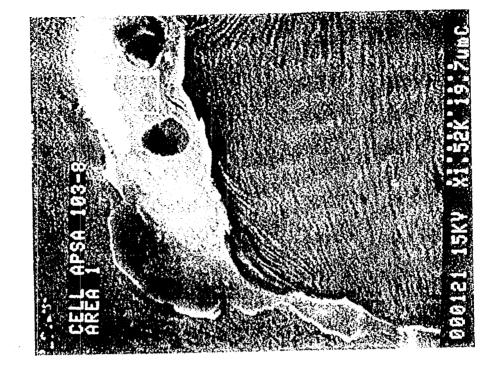


Figure 12A. 300 ×

Figure 12至 520 x Magnification

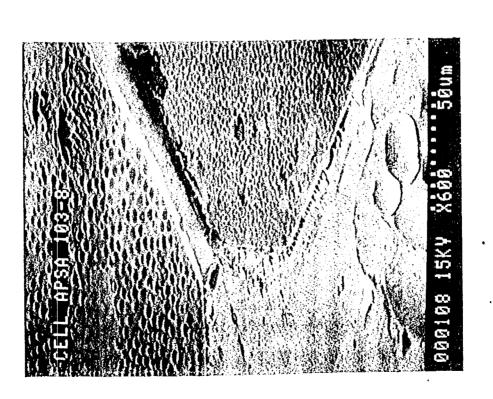


Figure 12C. 600 x Magnification

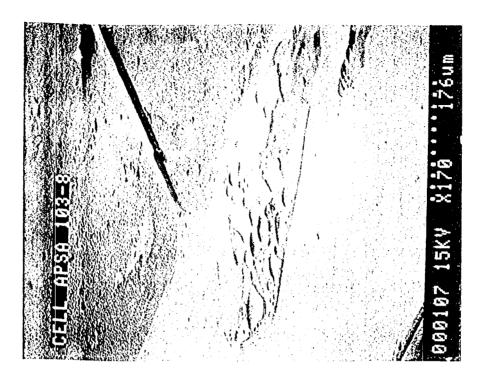
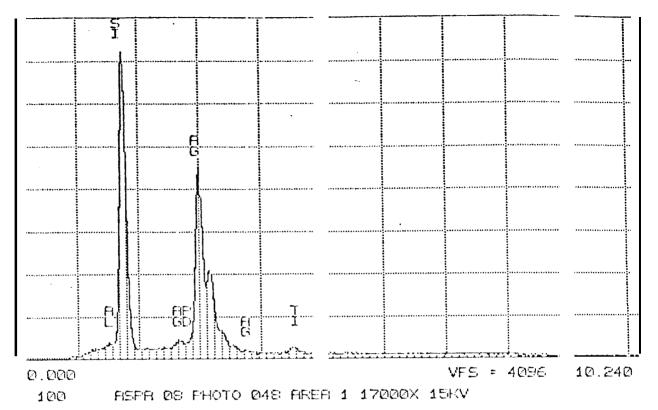


Figure 12D. 170 x Magnification

MATERIALSAND PROCESSES DE PARTMENT

Curson: 0.000 KeV = 0



SO: QUANTIFY

ASPA 08 PHOTO 048 AREA 1 17000X 15KV Standardless Analysis 15.0 kV 35.0 Degrees

Chi-sqd = 1.62

Element	Rel. K-ratio	Net Counts
A1 -K	0.00213 +/- 0.00164	313 +/- 241
Si-K	0.26995 +/- 0.00238	45229 +/- 398
F'd-L	0.01181 4/- 0.01056	987 +/- 883
Ag-L	0.67870 +/- 0.01487	48026 +/- 1052
Sn-L	0.01985 +/- 0.00793	1350 4/- 539
Ti-K	0.01756 +/~ 0.00192	1343 4/- 147

ZAF Correction 15.00 kV 35.00 deg No.of Iterations ≈ 1

Element K-ratio Z Al-K 0.002 0.90 Si-K 0.234 0.87 Fd-L 0.010 1.08 Ag-L 0.587 1.08 Sn-L 0.017 1.12 Ti-K 0.015 0.96	0 1.596 4 1.384 6 1.067 2 1.046 9 1.190	F 0.990 0.993 0.999 0.999 1.000	ZAF 1.422 1.2(2)1 1.160 1.131 1.343 1.169	Atom% 0.57 59.02 0.66 36.40 1.15 2.19	Wt% 0.26 -28.04 1.18 66.43 2.31 1.78 100.00%
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Figure 11. Cell No. APSA 08 EDX Chart, Area 1

SEM/ED* Image of APSA Ceil Damage Sites Induced during Reverse Biasing

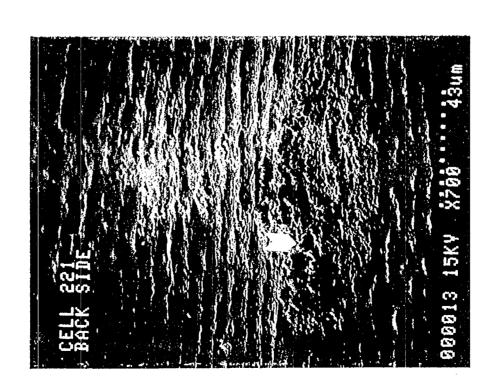
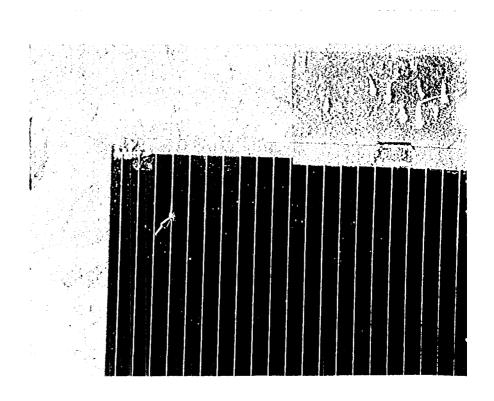




Figure 15A. 700 x Magnification

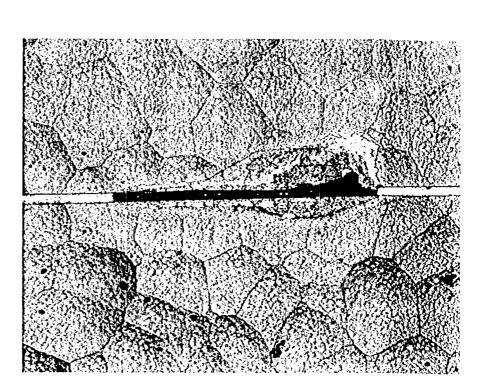
Figure 16B, 3000 ×

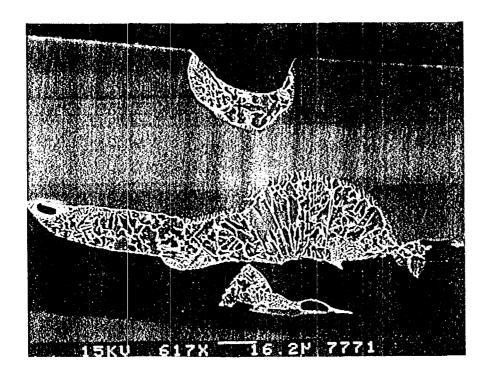
X8.2=M S/V 2 Overall view showing the failure site (arrow).



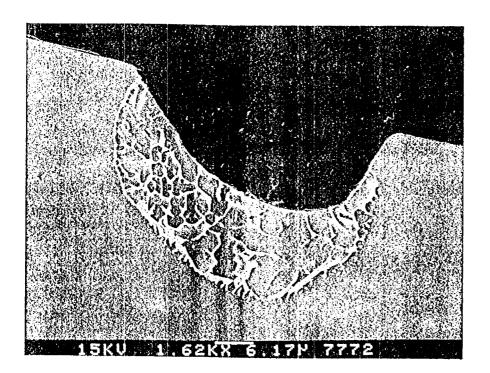
S/N 2
Detailed view showing the failure site which appears to be associated with electrical overstress damage (fusing of the Ag into the substrate).

X05= M





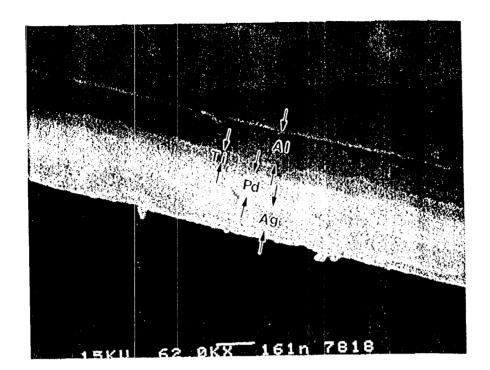
T=0°
SIN 2
Overall precision cross-sectional view showing the overstress damage site.



T=0°

S/N 2

Detailed cross-sectional view showing microalloying of the top Iuetalli7.alien into the silicon substrate.



T = 0°
S/N 111
Close-up view showing the backside metallization layers.